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30	22	((top or protective or sheet or template or lid or cover) same (glue or seal\$4 or adhesive\$5) same (photosensitive or photoreactive or photoresist) same pattern\$4 same (support or spacer or structure)) and ((top or protective or lid or sheet or template or cover) same (transmissive or transparent or translucent) same (die or circuit\$4 or function\$4 or imag\$4 or wafer)) and (encapsulat\$4 or encapsulant or packag\$3)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
31	12	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or encapsulant) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer or seal) same (photosensitive or photocur\$4 or photoresist or resist) same (outer or peripher\$4 or circumferen\$4))	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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32	12	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or encapsulant or template) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer or seal) same (photosensitive or photocur\$4 or photoresist or resist) same (outer or peripher\$4 or circumferen\$4))	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB